

CLAIMS

1. (currently amended) A method of forming a contact to a source/drain contact region of a transistor device having a gate, and the source/drain contact region is comprised substantially of ~~a first material silicon~~, the method comprising:

implanting particles including atoms having an atomic radius larger than an atomic radius of the atoms of the first material germanium into a region of the source/drain contact region at a dose not exceeding 1E17;

activating the atoms of the particles germanium implanted into the source/drain contact region;

implanting a source/drain dopant into the source/drain contact, wherein the implanting the source/drain dopant is performed subsequent to the activating the atoms; forming a metal nickel silicide over the source/drain contact region after the activating to form the contact.

2. (original) The method of claim 1 wherein the activating the atoms further includes activating the atoms in order to make the atoms substitutional in a lattice of the source/drain contact region, wherein the lattice includes atoms of the first material.

3. (original) The method of claim 1 wherein the activating the atoms increases a lattice constant of the lattice in the source/drain contact region.

4 - 6. (canceled)

7. (original) The method of claim 1 wherein the activating includes heating the source/drain contact region to a temperature of greater than 550 C.

8. (original) The method of claim 1 wherein the activating includes heating the source/drain contact region to a temperature of greater than 1000 C.

9. (original) The method of claim 1 wherein the activating further includes heating the source/drain contact region to a temperature in a range of approximately 900 – 1400 C.
10. (original) The method of claim 1 wherein the activating further includes rapid thermal annealing of the source/drain contact region.
11. (original) The method of claim 1 wherein the activating further includes laser annealing of the source/drain contact region.
12. (original) The method of claim 1 wherein the activating further includes arc lamp thermal annealing of the source/drain contact region.
13. (original) The method of claim 1 wherein the activating further includes gas convection annealing of the source/drain contact region.
14. (original) The method of claim 1 wherein the implanting the particles is performed at a temperature between 25 and 600 degrees Celsius.
- 15 - 16. (canceled)
17. (currently amended) The method of claim 1 further comprising:  
forming a sidewall spacer adjacent to a sidewall of the gate, wherein the implanting the particles germanium is performed prior to the forming the sidewall spacer.
18. (original) The method of claim 17 wherein the forming the sidewall spacer is performed prior to the implanting the source/drain dopant.
19. (original) The method of claim 1 wherein the gate is over a semiconductor substrate, the source/drain contact region is in the semiconductor substrate, and the source/drain contact region is disposed laterally from the gate.

20. (original) The method of claim 19 further comprising implanting a second source/drain dopant in the semiconductor substrate after the implanting the source/drain dopant, wherein the second source/drain dopant is implanted deeper than the source/drain dopant.
21. (currently amended) The method of claim 19 wherein the implanting the particles germanium further includes implanting with an energy of at least 3 keV.
22. (original) The method of claim 19 wherein the implanting the particles further includes implanting with an energy in the range of 3 keV to 50 keV.
23. (original) The method of claim 19 wherein the implanting the particles further includes implanting at a dose of at least 1E13 atoms per centimeter squared.
24. (original) The method of claim 19 wherein the implanting the particles further includes implanting at a dose in the range of 1E13 to 1E17 atoms per centimeter squared.
25. (original) The method of claim 19 wherein the implanting the particles is performed at a temperature between 25 and 600 degrees Celsius.
26. (currently amended) The method of claim 1, wherein:
  - the transistor has a second source/drain contact;
  - the implanting of the particles further includes implanting the particles into the second source/drain contact region at a dose not exceeding 1E17;
  - the activating of the atoms germanium further includes activating the atoms germanium of the particles implanted into the second source/drain contact region; and
  - the implanting of the source/drain dopant further includes implanting the source/drain dopant into the second source/drain contact region;further comprising forming a second metal silicide over the second region to form a second contact.
27. (original) The method of claim 1 wherein the source/drain dopant includes boron.

28. (original) The method of claim 1, wherein the gate is over a semiconductor substrate and a channel is in the substrate under the gate, further comprising forming a source/drain extension adjacent to the channel in the semiconductor substrate.
29. (canceled)
30. (original) The method of claim 28, wherein the forming comprises: implanting a second source/drain dopant into the substrate for forming the source/drain extension, wherein the implanting the second source/drain dopant is performed prior to the implanting the source/drain dopant.
31. (original) The method of claim 1 further comprising activating the source/drain dopant.
- 32 - 33. (canceled)
34. (currently amended) A method of forming a semiconductor device, the method comprising:  
implanting particles germanium into a region of a silicon substrate, ~~the substrate containing atoms of a first material, the particles including atoms having an atomic radius larger than an atomic radius of the atoms of the first material at~~  
~~a dose not exceeding 1E17;~~  
activating the atoms germanium implanted into the region of the substrate with a non diffusion activation process; and  
forming a metal nickel silicide over the second region after the activating.
35. (original) The method of claim 34 wherein the non diffusion activation process includes one of arc lamp rapid thermal annealing of the region and laser annealing of the region.
36. (currently amended) A method of forming a semiconductor device, the method comprising:  
forming a gate over a ~~semiconductor~~ silicon substrate, the substrate having a lattice having a lattice constant;

increasing the lattice constant of the lattice in a source/drain region of the substrate after  
the forming the gate by implanting germanium;  
implanting a source/drain dopant into the ~~substrate for forming at least a portion of a~~  
~~source/drain region in the substrate~~ source/drain region, wherein the implanting  
the source/drain dopant is performed subsequent to the increasing the lattice  
constant at a dose not exceeding 1E17;  
forming a metal nickel silicide over the portion of the source/drain region.

37 - 41. (canceled)

42. (original) The method of claim 36 wherein the source/drain dopant includes boron.

43. (original) The method of claim 36 wherein the source/drain dopant includes a  
source/drain extension dopant for forming a source/drain extension in substrate.

44. (currently amended) A method of forming a semiconductor device, the method  
comprising:

forming a gate over a silicon semiconductor substrate;  
implanting particles including germanium into a region of the substrate after the forming  
the gate at a dose not exceeding 1E17;  
activating the germanium implanted into the region;  
implanting a source/drain dopant into the substrate for forming at least a portion of a  
source/drain region in the substrate, wherein the implanting the source/drain  
dopant is performed subsequent to the activating the germanium;  
forming a nickel silicide over the region after the activating.

45. (currently amended) In a transistor device structure having a gate stack and source/drain  
contact regions comprised primarily of a first material, wherein the source/drain contact regions  
have a lattice constant, a method of forming a contact, comprising:

implanting particles including atoms having an atomic radius larger than an atomic radius of the atoms of the first material germanium at a dose not exceeding 1E17 into the source/drain contact regions;

activating the atoms of the particles germanium implanted into the source/drain contact regions to increase the lattice constant of the source/drain contact regions; forming a metal nickel silicide over the source/drain contact regions after the activating of the atoms.

46. (original) The method of claim 45, further comprising doping the source/drain contact regions with P-type material after activating the atoms and prior to forming the metal silicide.

47. (canceled)